

## REMARKS

Examiner K. Rose is thanked for the continued thorough Search and Examination of the subject Application for Patent.

It is respectfully pointed out that the Office Action dated April 10, 2003 replaced the Office Action dated March 20, 2003.

Claim 11 has been amended to include the limitations of Claim 13. Claim 13 has been cancelled without prejudice. The basis for this amendment to Claim 11 can be found in Claim 13.

Claim 11, 12, and 14-19 have been amended to make the preamble of the claims more descriptive of the claims. The basis for this amendment to Claims 11, 12, and 14-19 can be found in the Title of the Invention and in the Specification on page 1, lines 5-9. This amendment to Claims 11, 12, and 14-19 serve only to make the preamble of the claims more descriptive of the claims and no new issues are introduced.

Reconsideration of the Rejection of Claims 11, 12, 14-16, and 19, as amended, under 35 U.S.C. 103(a) as being unpatentable over Applicant's Prior Art (Figures 1 and 4) in view of Huang et al. (U.S. Pat. No. 5,961,912) is requested. Claim 13 was included in this Rejection but has been cancelled without prejudice. Claims 11, 12, 14-16, and 19, as amended, describe a molded package with a disposable mold runner

gate having a barrier material formed over a gating area of a substrate wherein the adhesion between the barrier material and the substrate is low and the barrier material is later peeled away and discarded. Conductive traces can be formed in the gating areas of the substrate. Key limitations of Claims 11, 12, 14-16, and 19, as amended, are "some of said conductive traces are formed in said gating area of said first surface of said substrate"; "barrier material attached to said gating area of said substrate"; and "encapsulation material formed over a part of said barrier material attached to said gating area of said substrate, thereby forming a mold runner, wherein said barrier material and said encapsulation material are chosen so that the adhesion of said barrier material to said substrate is less than the adhesion of said barrier material to said encapsulation material".

Figs. 1 and 4 of Applicant's prior art show a substrate having a mold runner 33 formed over a gating region 36, see Fig. 4. The Applicant's prior art does not show nor describe conductive traces formed in the gating area of the first surface of the substrate.

Huang et al. describe an encapsulation method for a substrate based electronic device. Huang et al. neither show nor describe conductive traces formed in the gating area of the first surface of the substrate. Huang et al. describe the use of a shim placed on the substrate, but not attached to the substrate, to prevent encapsulation material from contacting the top surface of the substrate. This pre placed shim described by Huang et al. is different from the "barrier material attached to said gating area of said substrate" described in Claims 11, 12, 14-16, and 19.

The Applicant's prior art does not show nor describe conductive traces formed in the gating area of the first surface of the substrate. Huang et al. do not show nor describe conductive traces formed in the gating area of the first surface of the substrate, nor make conductive traces formed in the gating area of the first surface of the substrate an obvious extension of the Applicant's prior art. Reconsideration of the Rejection of Claims 11, 12, 14-16, and 19 under 35 U.S.C. 103(a) as being unpatentable over Applicant's Prior Art (Figures 1 and 4) in view of Huang et al. (U.S. Pat. No. 5,961,912); and Allowance of Claims 11, 12, 14-16, and 19; are requested. Claim 13 was included in this Rejection but has been cancelled without prejudice.

It is respectfully pointed out that the Examiner has not indicated any rejection of Claims 17 and 18 in this Office Action. Since Claims 17 and 18 have not been rejected, we assume that Claims 17 and 18 are allowable.

It is requested that should Examiner Rose not find that the Claims are now Allowable that the Examiner call the undersigned Agent at (845)-462-5363 to overcome any problems preventing allowance.

Respectfully submitted,



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